

Int'l Electron Device Parley To Air LSI, Packaging, Profit

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WASHINGTON. — The inevitable transition of large-scale integration from wish to wafer and the future problems of packaging and profits will be the fulcrum of the technical program at the 1967 International Electron Devices Meeting which opens here Wednesday.

Schemes and schematics for translating LSI into the everyday world of electronic hardware, and the static expected, will cut across the keynote session, luncheon meeting, three invited papers, and a panel discussion — which just about exhausts available media at the event.

The meeting will span three days at IED's annual roost, the Sheraton-Park Hotel.

Those who last year felt that LSI was more message than message may be in for a rude awakening this time as new applications and production techniques unfold in many of the 175 papers scheduled.

Since last year, LSI has been moving, quietly and at snail's pace into designs of new military equipment scheduled for delivery next year. Some hint of new

programs, including non-military LSI hardware, is expected at the meeting.

Luncheon Talk.

The impact of the new technology on the present third generation so-called and the implications of integrated electronics for the industry of the future will be the burden of a luncheon talk by Patrick E. Haggerty, chairman of the board and chief executive officer of Texas Instruments.

The former TI president, who has transplanted the oracular art from Delphi to Dallas so far as the electronics industry is concerned, will examine the dollars and cents aspects of integrated electronics and the areas of future use in all major markets.

Conference officials expect the



Dr. Gordon Moore
Veteran Panelist

talk to be "as important a milestone for the broad future of integrated electronics" as was a previous pronouncement on the subject made by Mr. Haggerty at IEEE some years back. At that time, it was called "modular magic" and LSI was eight "gate" functions on a single chip. This year, Mr. Haggerty's company will be talking 800 gates in a flat pack.

Some of this talk will again come from TI's articulate LSI spokesman, Richard L. Petritz, who will moderate a panel of well known LSI cognoscenti — Gordon Moore (Fairchild), Jim Early (Bell Labs), Jan Narud (Motorola), C. G. Thornton (Philco Ford), and Gerald Herzog (RCA-Princeton).

LSI Technology.

While the general field of integrated electronics will concern eight of the 29 technical sessions, LSI technology specifically will be the core of six papers covering recent advances in high yield processing technology, new developments in isolation structures, hybrid LSI. Beam lead and new mounting and bonding techniques will be scrutinized.

Microwave integrated electronics, perhaps the newest branch of the monolithic art, will also

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